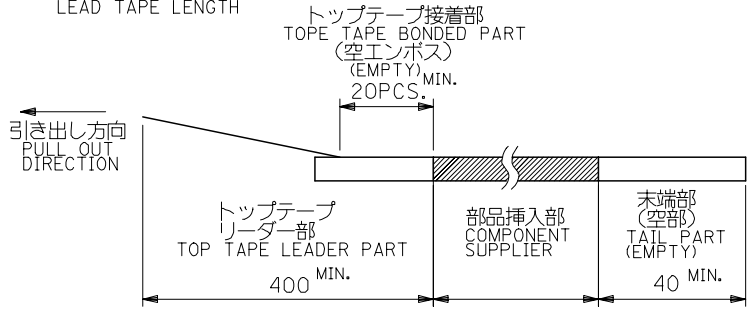
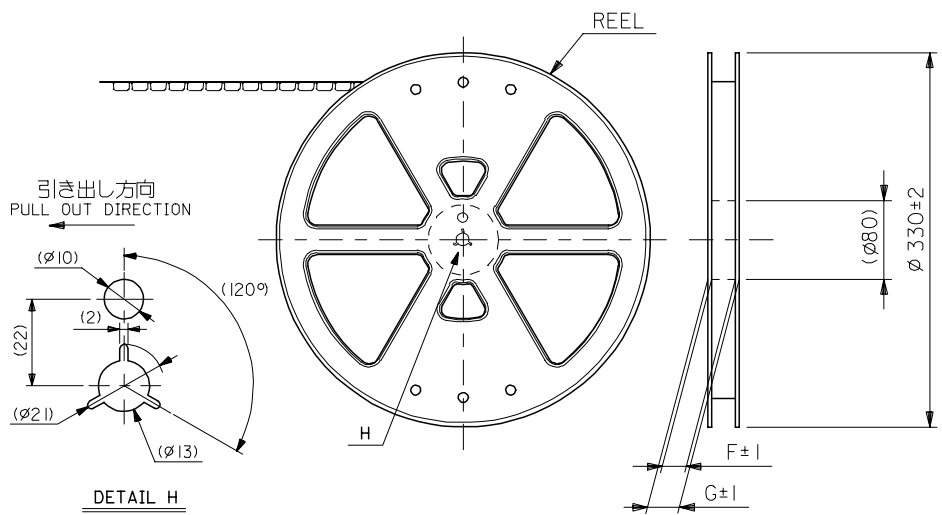


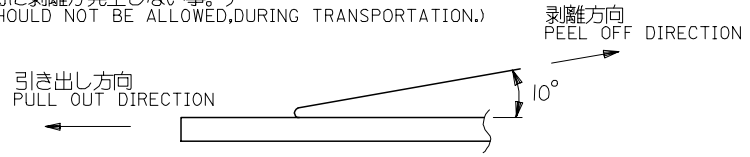
注)
NOTES

1. 製品番号 55650-***81 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55650-***81 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：2000個/リール
NUMBER OF CONNECTORS:2000 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0. 1~1. 3N {10~130gf}

尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED,DURING TRANSPORTATION.)

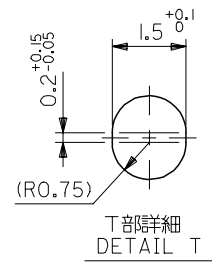
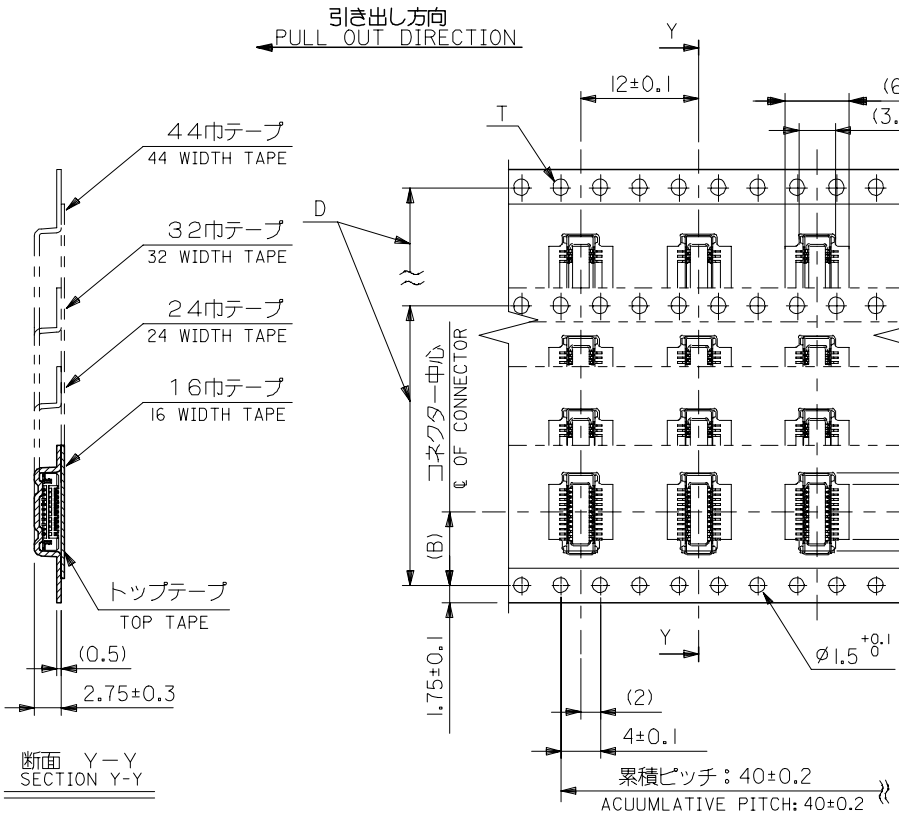


5. 材料
MATERIAL
キャリアテープ：ポリプロピレン (PP)
CARRIER TAPE:POLYPROPYLENE(PP)
トップテープ：PET, PE, PEF
TOP TAPE:PET,PE,PEF
リール：ポリスチレン
REEL : POLYSTYRENE

6. 本製品は 55650-***8 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***8.

55650-***78 MODEL NO.

REVISED EC NO: J2007-0848 DRWN: A0YAGI 2006/10/31 CHKD: KTOYODA 2006/11/01 APPR: NUKITA 2006/11/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/02/17	TITLE EMBOSSSED TAPE PACKAGE FOR 55650-***81 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/02/17	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/17	DOCUMENT NO. SD-55650-012			
	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 2		SHEET NO. 1 OF 2			
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

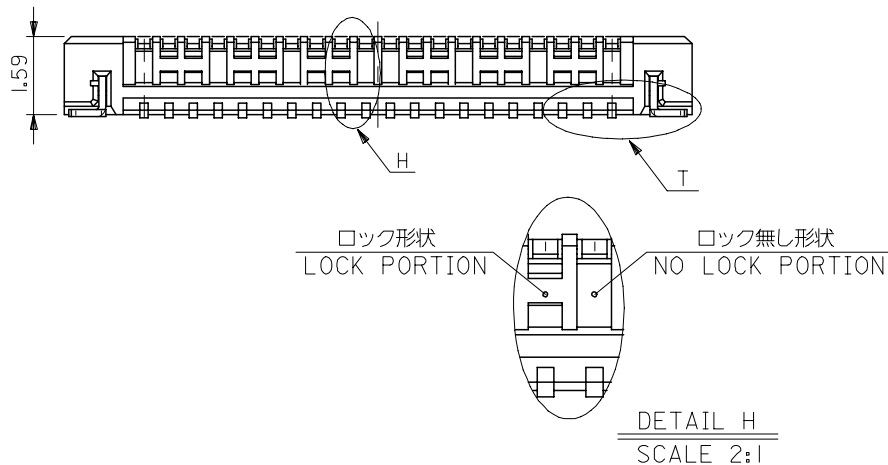
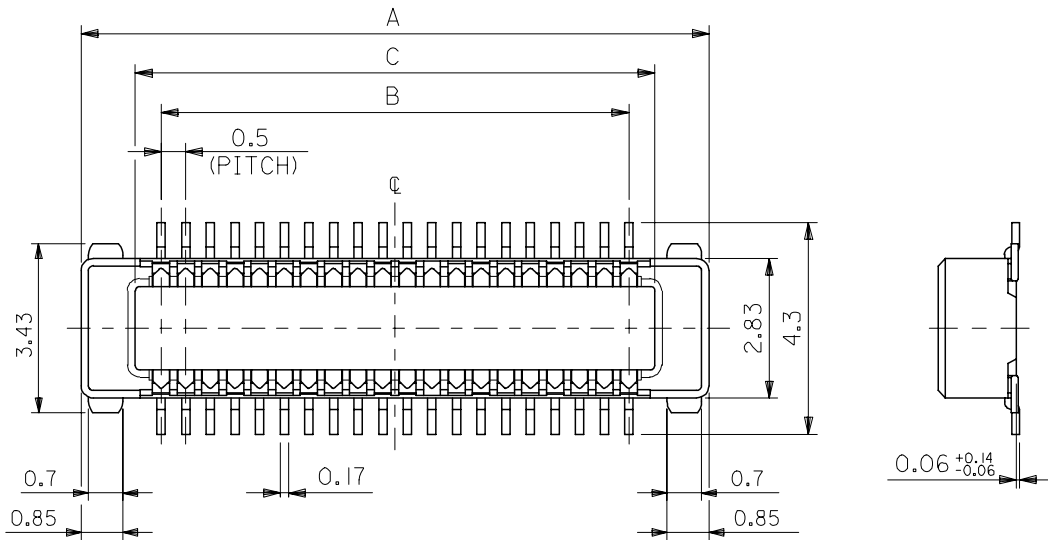


37.4	33.4	32±0.3	28.4	17.95	14.2	15.55	55650-6078	60	
				15.45		13.05	55650-5078	50	
29.4	25.4	24±0.3		12.95	11.5	10.55	55650-4078	40	
				10.45		8.05	55650-3078	30	
G	F	E キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2007-0848 DRWN: A0YAGI 2006/10/31 CHKD: KTOYODA 2006/11/01 APPR: NUKITA 2006/11/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/02/17	TITLE EMBOSSD TAPE PACKAGE FOR 55650-**81 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/02/17	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/17	DOCUMENT NO. SD-55650-012		SHEET NO. 2 OF 2	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART				
A		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

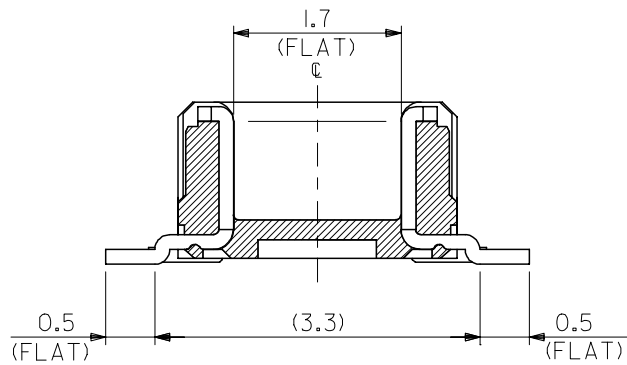
注記
NOTES:

- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
錫メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 54363-****
MATED CONN.: 54363-****
- 本製品は55650-****1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-****1

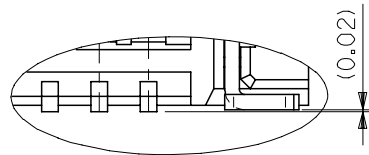


—#	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

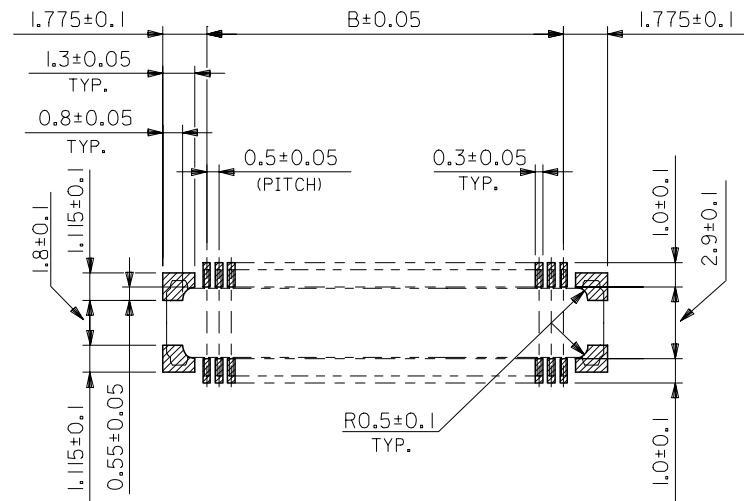
REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKD: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-013	SHEET NO. 1 OF 2	
	ANGULAR	±3 °	MATERIAL NO. SEE TABLE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



製品断面図 (半田付け部、吸着面寸法)
 DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
 T部詳細



推奨基板寸法
 RECOMMENDED PCB PATTERN LAYOUT
 (SCALE 5:1)

REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKD: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 ^{OVER} 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
	30 ^{OVER}	± 0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO.	DOCUMENT NO. SD-55650-013	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	SEE SHEET 1				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					